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ABSTRACT

SEMICONDUCTOR DEVICE PACKAGE AND METHOD OF MANUFACTURE

A semiconductor package is disclosed. The package includes a substrate; a semiconductor die attached to the substrate; a housing part attached to the substrate and arranged to surround the semiconductor die; and solidified
5 moulding material arranged around the housing and adhering to the substrate to secure the housing in position on the substrate. A method of manufacturing the package is also disclosed.

Figure 2.

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